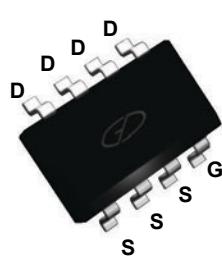
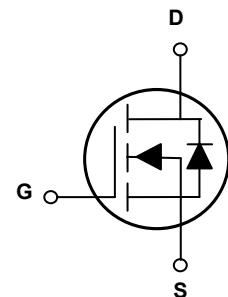


## Main Product Characteristics

$V_{(BR)DSS}$	40V
$R_{DS(ON)}$	9mΩ
$I_D$	9A



SOP-8



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The SSFQ4906 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit	
Drain-Source Voltage	$V_{DS}$	40	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	
Drain Current-Continuous ( $T_A=25^\circ\text{C}$ )	$I_D$	9	A	
Drain Current-Continuous ( $T_A=100^\circ\text{C}$ )		5.7		
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )		15		
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		9.5		
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	36	A	
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	76	mJ	
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	39	A	
Power Dissipation ( $T_A=25^\circ\text{C}$ )	$P_D$	1.47	W	
		0.012	W/°C	
(T <sub>C</sub> =25°C) Derate above 25°C		5.4	W	
		1.47	W/°C	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W	
Operating Junction Temperature Range	$T_J$	-55 To +150	°C	
Storage Temperature Range	$T_{STG}$	-55 To +150	°C	

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	-	-	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\triangle \text{BV}_{\text{DSS}}/\triangle T_J$	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	0.03	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$ $V_{\text{DS}}=32\text{V}, V_{\text{GS}}=0\text{V}, T_J=85^\circ\text{C}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$ $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$	-	7	9	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\triangle V_{\text{GS}(\text{th})}$		-	-5	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=10\text{A}$	-	13	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2,3</sup>	$Q_g$	$V_{\text{DS}}=20\text{V}, I_{\text{D}}=8\text{A}$ $V_{\text{GS}}=4.5\text{V}$	-	12.2	24	nC
Gate-Source Charge <sup>2,3</sup>	$Q_{\text{gs}}$		-	3.3	7	
Gate-Drain Charge <sup>2,3</sup>	$Q_{\text{gd}}$		-	6.7	13	
Turn-On Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, R_{\text{G}}=3.3\Omega$ $V_{\text{GS}}=10\text{V}, I_{\text{D}}=1\text{A}$	-	13.2	25	ns
Rise Time <sup>2,3</sup>	$t_r$		-	2.2	5	
Turn-Off Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{off})}$		-	72	130	
Fall Time <sup>2,3</sup>	$t_f$		-	4.5	10	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	1220	2200	pF
Output Capacitance	$C_{\text{oss}}$		-	130	250	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	55	110	
Gate Resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	2.2	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$	$V_G=V_D=0\text{V},$ Force Current	-	-	15	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	30	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_s=1\text{A}, T_J=25^\circ\text{C}$	-	-	1	V
Reverse Recovery Time	$T_{\text{rr}}$	$V_{\text{GS}}=0\text{V}, I_s=1\text{A},$ $dI/dt=100\text{A}/\mu\text{s}$	-	17	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	2.8	-	nC

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

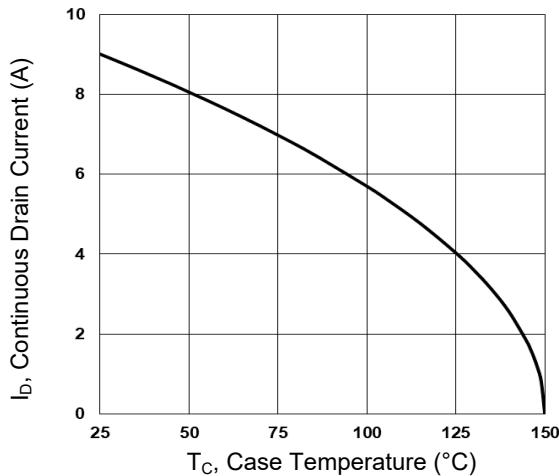


Figure 1. Continuous Drain Current vs. T<sub>C</sub>

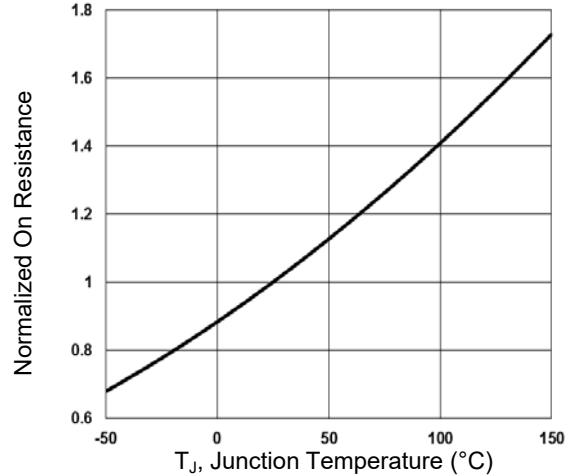


Figure 2. Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

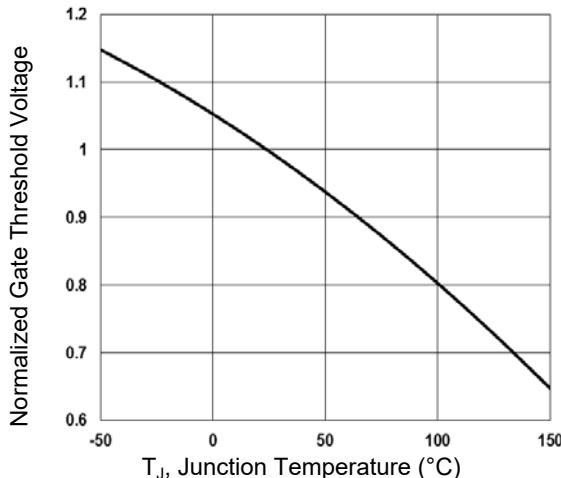


Figure 3. Normalized V<sub>th</sub> vs. T<sub>J</sub>

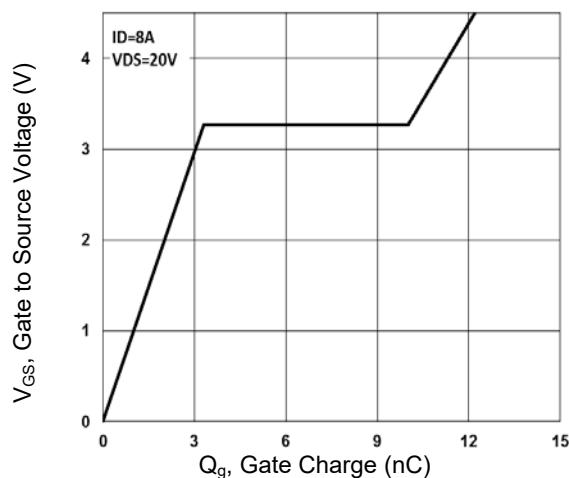


Figure 4. Gate Charge Waveform

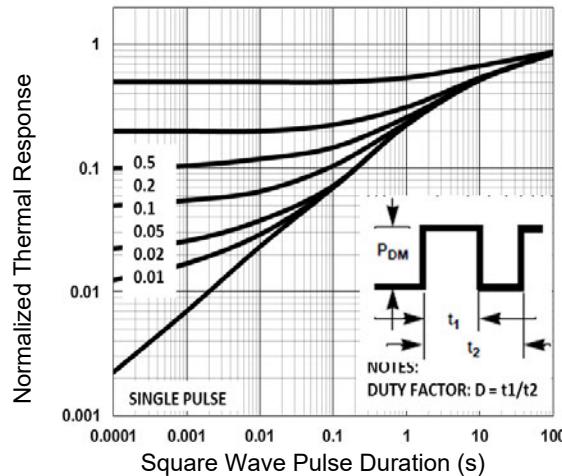


Figure 5. Normalized Transient Impedance

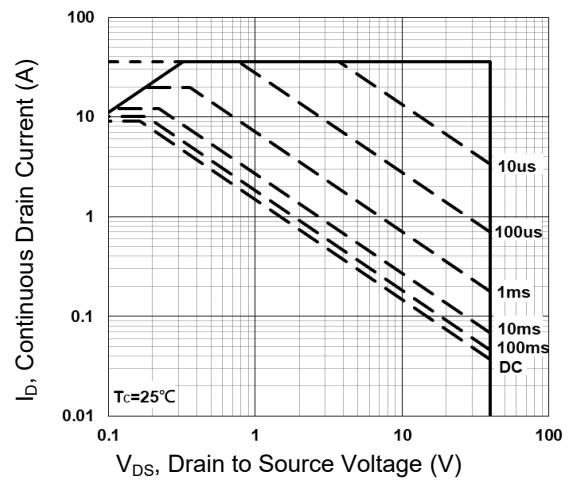
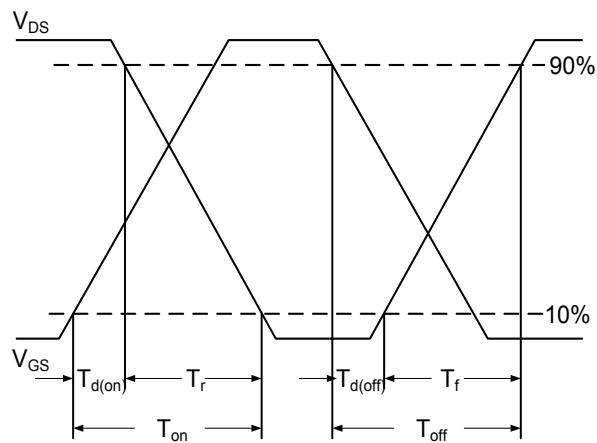


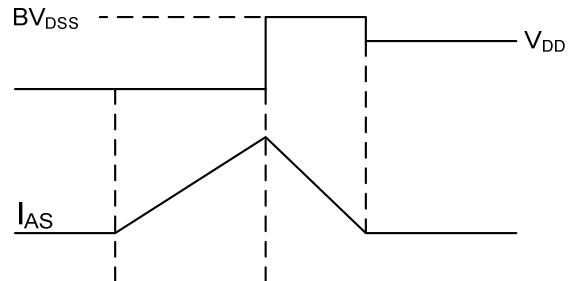
Figure 6. Maximum Safe Operation Area

### Typical Electrical and Thermal Characteristic Curves



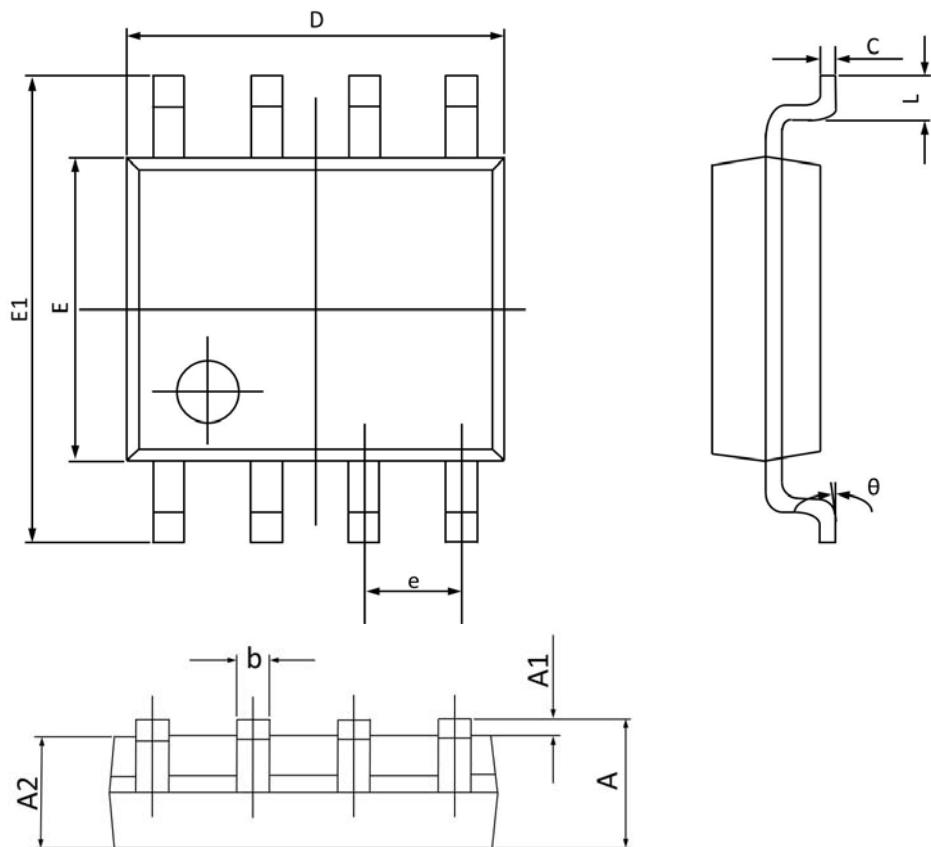
**Figure 7. Switching Time Waveform**

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$



**Figure 8. EAS Waveform**

### Package Outline Dimensions (SOP-8)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	1.350	1.800	0.053	0.069
A1	0.050	0.250	0.002	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.300	0.510	0.012	0.020
c	0.150	0.260	0.006	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270 BSC		0.050 BSC	
h	0.250	0.500	0.010	0.020
L	0.400	1.000	0.016	0.039
L1	1.050 BSC		0.041 BSC	
$\theta$	0°	8°	0°	8°